

Title (en)
PROCESS FOR ELECTROPLATING METALLIC AND METALL MATRIX COMPOSITE FOILS, COATINGS AND MICROCOMPONENTS

Title (de)
VERFAHREN ZUR ELEKTROPLATTIERUNG VON METALLISCHEN UND METALL-MATRIX-COMPOSITE FOLIEN, BESCHICHTUNGEN UND MIKROKOMPONENTEN

Title (fr)
PROCEDE DE PLACAGE ELECTROCHIMIQUE DE FEUILLES METALLIQUES ET DE COMPOSITES A MATRICE METALLIQUE, DE REVETEMENTS ET DE MICROCOMPOSANTS

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Application
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Priority
EP 0207023 W 20020625

Abstract (en)
[origin: EP1826294A1] The invention relates to a process for forming coatings or free-standing deposits of nanocrystalline metals, metal alloys or metal matrix composites. The process employs drum plating or selective plating processes involving pulse electrodeposition and a non-stationary anode or cathode. Novel nanocrystalline metal matrix composites and micro components are disclosed as well. Also described is a process for forming micro components with grain sizes below 1,000nm.

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WO 2004001100 A1 20031231; AT E387522 T1 20080315; AU 2002321112 A1 20040106; AU 2002321112 B2 20080703; BR 0215787 A 20050301; BR 0215787 B1 20131203; CA 2490464 A1 20031231; CA 2490464 C 20080902; DE 60225352 D1 20080410; DE 60225352 T2 20080612; DK 1516076 T3 20080623; EP 1516076 A1 20050323; EP 1516076 B1 20080227; EP 1826294 A1 20070829; ES 2301666 T3 20080701; HK 1075278 A1 20051209; IL 165904 A0 20060115; JP 2005530926 A 20051013; KR 100890819 B1 20090406; KR 20050024394 A 20050310; MX PA04011940 A 20050331; PT 1516076 E 20080311; ZA 200410368 B 20060726

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